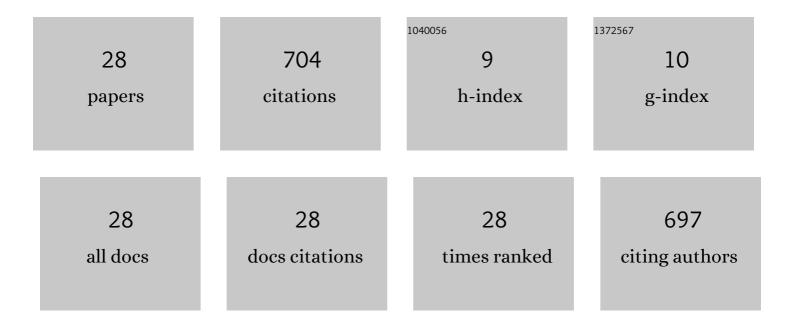
## Nicholas R Jankowski

List of Publications by Year in descending order

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| #  | Article  | IF   | CITATIONS |
|----|--|------|-----------|
| 1  | Kapitza Resistance at the Two-Dimensional Electron Gas Interface. , 2019, , .  |      | 6         |
| 2  | Experimental evaluation of metallic phase change materials for thermal transient mitigation.<br>International Journal of Heat and Mass Transfer, 2018, 116, 512-519. | 4.8  | 52        |
| 3  | Thermodynamic cycle optimization for pyroelectric energy conversion in the thin film regime.<br>International Journal of Energy Research, 2017, 41, 1880-1890.       | 4.5  | 14        |
| 4  | Voiding Effects on the Thermal Response of Metallic Phase Change Materials Under Pulsed Power<br>Loading. , 2017, , .  |      | 4         |
| 5  | Thermal Model of a Thin Film Pulsed Pyroelectric Generator. , 2016, , .  |      | 2         |
| 6  | Numerical Evaluation of Multiple Phase Change Materials for Pulsed Electronics Applications. , 2016, ,   |      | 6         |
| 7  | Wireless Power Transmission via Modulated Laser Irradiation of Pyroelectric Thin Films. Advanced<br>Materials Technologies, 2016, 1, 1600178.                        | 5.8  | 15        |
| 8  | Measurement of High-Performance Thermal Interfaces Using a Reduced Scale Steady-State Tester and<br>Infrared Microscopy. Journal of Heat Transfer, 2016, 138, .      | 2.1  | 14        |
| 9  | Nonintrusive Optical Validation of Two-Phase Flow Regimes in a Small-Diameter Tube. Heat Transfer<br>Engineering, 2016, 37, 972-984.                                 | 1.9  | 3         |
| 10 | Two-Phase Thermal Ground Planes: Technology Development and Parametric Results. Journal of Electronic Packaging, Transactions of the ASME, 2015, 137, .              | 1.8  | 59        |
| 11 | Non-Intrusive Optical Validation of Two-Phase Flow Regimes in a Small Diameter Tube. , 2014, , .   |      | 2         |
| 12 | A review of phase change materials for vehicle component thermal buffering. Applied Energy, 2014, 113, 1525-1561.  | 10.1 | 343       |
| 13 | Modified Model for Improved Flow Regime Prediction in Internally-Grooved Tubes. , 2013, , .  |      | 2         |
| 14 | Analysis and Characterization of Thermal Expansion-Matched Wick-Based Multi-Chip Passive Heat<br>Spreaders in Static and Dynamic Environments. , 2013, , .           |      | 2         |
| 15 | Interfacial Resistance Measurement of High Performance Thermal Interface Materials. , 2013, , .  |      | 1         |
| 16 | Thermal performance of a flat polymer heat pipe heat spreader under high acceleration. Journal of Micromechanics and Microengineering, 2012, 22, 045018.             | 2.6  | 53        |
| 17 | GaN HEMT Junction Temperature Dependence on Diamond Substrate Anisotropy and Thermal Boundary<br>Resistance. , 2012, , .   |      | 7         |
| 18 | Numerical investigation and sensitivity analysis of manifold microchannel coolers. International<br>Journal of Heat and Mass Transfer, 2012, 55, 7698-7708.          | 4.8  | 57        |

| #  | Article   | IF  | CITATIONS |
|----|---|-----|-----------|
| 19 | Two-Phase Minichannel Cold Plate for Army Vehicle Power Electronics. , 2011, , .  |     | 4         |
| 20 | The Impact of GaN/Substrate Thermal Boundary Resistance on a HEMT Device. , 2011, , .   |     | 11        |
| 21 | Experimental Investigation of a Flat-Plate Oscillating Heat Pipe During High-Gravity Loading. , 2011, , .   |     | 5         |
| 22 | Numerical Study on the Thermal Performance of a Substrate Integrated Thermal Buffer Heat Sink. , 2011, , .  |     | 1         |
| 23 | Electrical Supercooling Mitigation in Erythritol. , 2010, , .   |     | 11        |
| 24 | Thermal performance of a Direct-Bond-Copper Aluminum Nitride manifold-microchannel cooler. , 2010, , .  |     | 5         |
| 25 | Design and Fabrication of a Substrate Integrated Phase Change Thermal Buffer Heat Sink. , 2009, , .   |     | 1         |
| 26 | A Micromachined Manifold Microchannel Cooler. , 2009, , .   |     | 5         |
| 27 | Stereolithographically fabricated aluminum nitride microchannel substrates for integrated power electronics cooling. Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems, 2008, , . | 0.0 | 9         |
| 28 | Comparing Microchannel Technologies to Minimize the Thermal Stack and Improve Thermal<br>Performance in Hybrid Electric Vehicles. , 2007, , .   |     | 10        |